

ABSTRACT

A shielding apparatus for EMI-sensitive electronic components, especially for radio transmitting devices and/or radio receiving devices of telecommunication terminals for contactless telecommunication, such as cordless telephones and mobile telephones and similar, which can be constructed without using expensive manufacturing and assembly steps without any extra space requirement. The EMI-sensitive electronic components and/or circuits are arranged on a separate, at least double-layered printed circuit board and are embodied as a printed circuit board module. Said circuit board and another separate, at least two-layered circuit board which includes a recess for the EMI-sensitive electronic components and/or circuits and which is embodied in the form of a base printed circuit board, are joined together by soldering, preferably in the region of contact areas, to form a unit such that a cage is formed by the recess which is disposed between two metal surfaces being respectively connected to the shielding surfaces by means of continuous, highly adjacent contacts. The cage shields the EMI-sensitive electronic components and/or circuits on all sides.